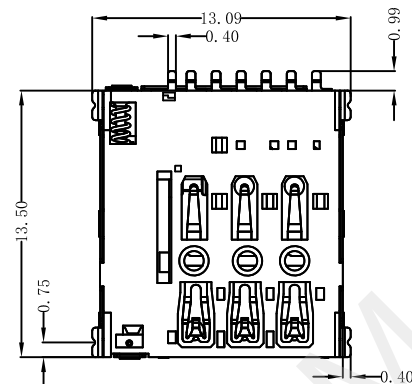
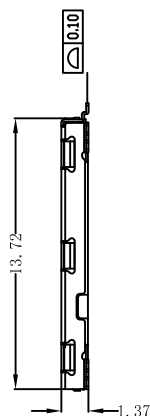
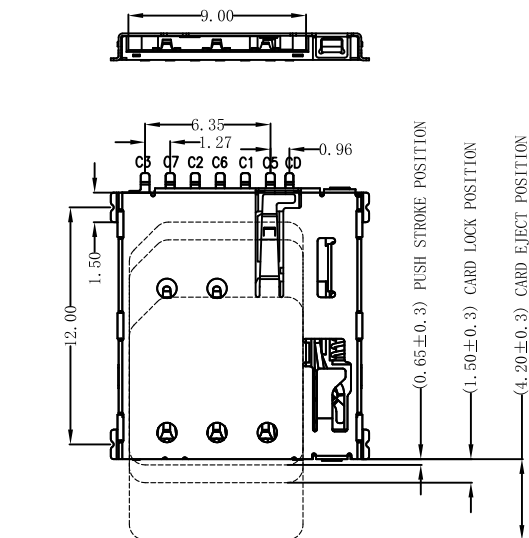
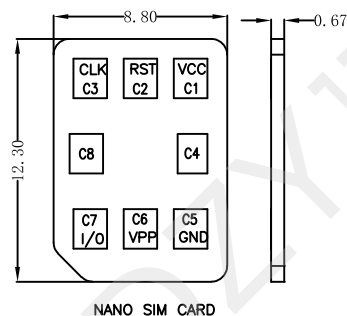
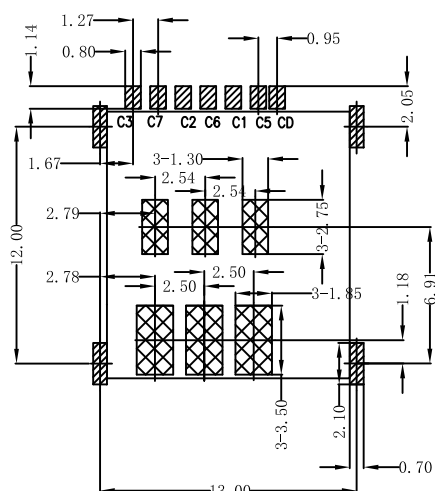


NOTES:

- MATERIAL:
HOUSING:HI-TEMP. PLASIC UL 94V-0
CONTACT:COPPER ALLOY
SHELL:STAINLESS STEEL
- PLATING :
TERMINAL:
CONTACT AREA: Au GOLD FLASH.
SOLDER AREA: AU GOLD FLASH.
UNDER PLATE: NICKEL.
SHELL: NICKEL PLATED OVER ALL.
SOLDER AREA: GOLD FLASH.
- SPECIALITY:
3.1 Rated current:1.0A
3.2 Rated voltage:30V
3.3 Contact Resistance:100mΩ MAX
3.4 Insulation Resistance:1000MΩ MIN 500V DC
3.5 Dielectric withstanding voltage: 500V AC.
3.6 Solder ability:260+0/-5℃ 30±10s.
3.7 Durability:5000 Cycles Min.
3.8 Operating condition:Temperature-40℃ +85℃
Humidity 80% R.H MAX



SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

▨ PAD
▩ KEEP OUT AREA



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TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X." ±2" X.X" ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: NANO SIM PUSH 1.37H 带CD PIN 无柱	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC381-SIM07-137	MOLD NO.
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-2510221052	SHEET NO. 1 OF 1